



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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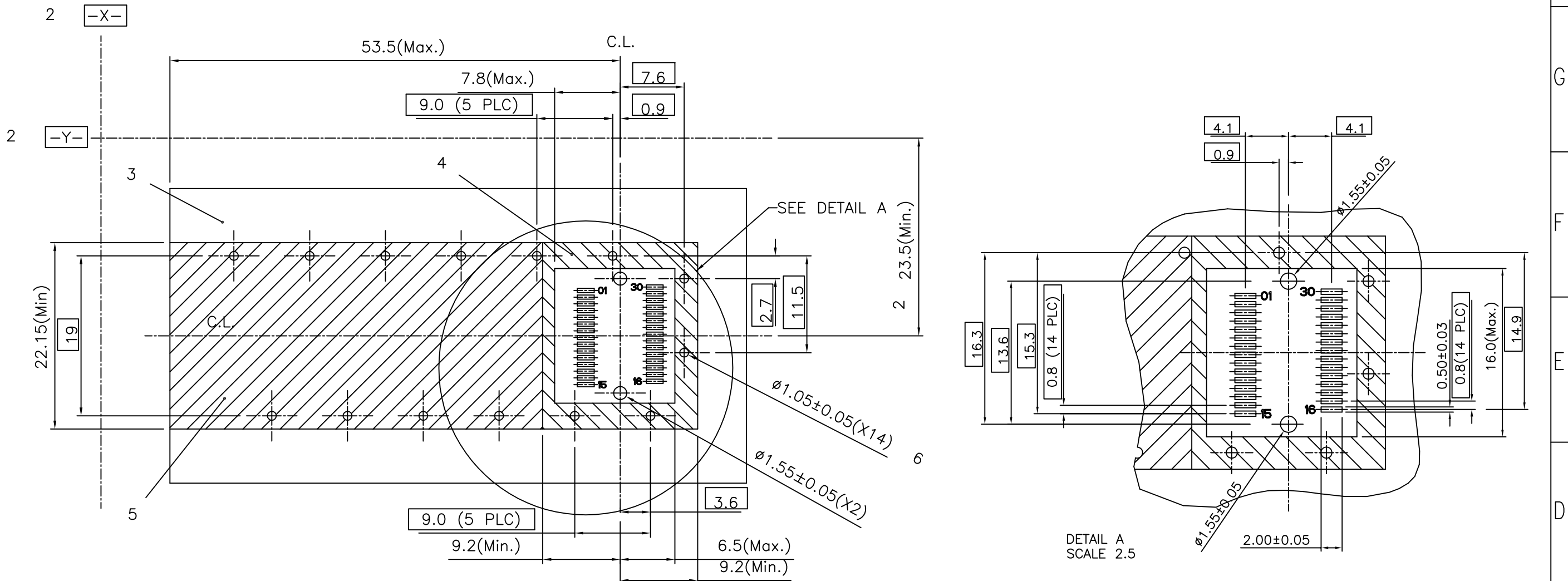
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REVISION RECORD				
REV	ECO	DESCRIPTION	DRFT	CHKD



RECOMMEND P.C.B. LAYOUT

Note:

- |  |   |
|--|---|
| <p>1 DESIGN MEETS REQUIREMENTS OF XFPMSA SPECIFICATION REV. 3.1 (10 GIGABIT SMALL FROM FACTOR PLUGGABLE MODULE).</p> <p>2 DATUM <math>\boxed{-X-}</math> AND <math>\boxed{-Y-}</math> ESTABLISHED BY CUSTOMER.</p> <p>3 DATUM <math>\boxed{-A-}</math> IS TOP SURFACE OF HOST BOARD.</p> <p>4 INDICATED SURFACES TO BE CONDUCTIVE AND CONNECTED TO CHASSIS GROUND.</p> | <p>5 CROSS-HATCHED AREA DENOTES COMPONENT AND TRACE KEEP-OUT (EXCEPT CHASSIS GROUND)</p> <p>6 RECOMMENDATION FOR P.C.BOARD HOLES:<br/>                 A. HOLE <math>\phi</math> AFTER DRILLING : <math>1.15 \pm 0.02</math> mm.<br/>                 B. HOLE <math>\phi</math> Sn PLATE : <math>1.05 \pm 0.05</math> mm.<br/>                 C. 25um ~ 50um COPPER UNDERPLATE.</p> <p>7 -CAUTION- REFLOW PROCESS WILL DAMAGE CAGE ASSEMBLY.</p> |
|--|---|

DETACHED LISTS	MM (INCH)	DFTO tzou	DATE 06/02/06'	<b>FULL RISE ELECTRONIC CO., LTD</b> (Non-Logo) XFP CAGE WITH PCI HEAT SINK KIT		
	TOLERANCES EXCEPT AS NOTED		CHKD			DATE
			MFO			DATE
			APPVL			DATE
.0 ± 0.2 ± .00 ± 0.15 ± .000 ± 0.075 ±		MATERIAL :		TITLE		
ANGLES ± 0.5		QT'Y :		DRAWING NO. XFPO03-L		
THIRD ANGLE PROJECTION		FINISH :		/PART NO. SEE NOTE		
		SCALE : 1 : 2		DO NOT SCALE DRAWING		
				SIZE A3	REV 0	
				SHEET 2	OF 2	